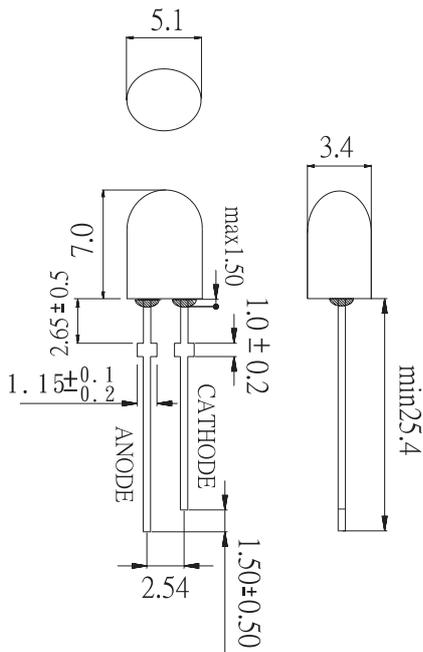


## Device Selection Guide

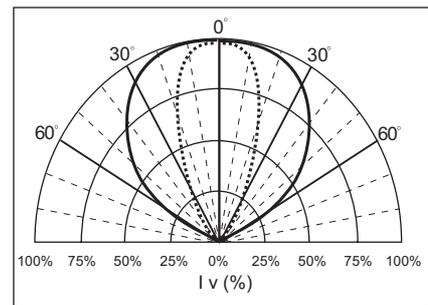
Part Number EOL-	Luminous Intensity $I_V$ (mcd) @ $I_F = 20$ mA		Viewing Angle $2\theta_{1/2}$	Dominant Wavelength $\lambda_D$ (nm) @ $I_F = 20$ mA	$V_F$ @ $I_F = 20$ mA		$I_R$ ( $\mu$ A) @ $V_R = 5$ V	Stand Off	Epoxy Color
	Min.	Typ.	Typ.	Typ.	Typ.	Max.	Max.		
HEBTDD0-EG	120	190	105/45°	470	3.4	4.0	50	Yes	Blue Diffused

BIN#	K	L	M		
Intensity(mcd) @ $I_F = 20$ mA	120-170	170-240	240-335		

## Package Dimensions



## Beam Pattern



### Note:

- All dimensions are in millimeter (mm).
- Unspecified tolerance:  $\pm 0.20$ mm.
- Protruded resin 1.5mm max.
- Lead spacing is measured where the leads emerge from the package
- Specifications are subject to change without notice.

## Absolute Maximum Ratings at $T_A = 25^\circ\text{C}$

Parameter	Symbol		<i>USER---APPROVED</i>
Peak Forward Current	$I_{fm}$	50mA	
Average Forward Current	$I_f$	20mA	
Reverse Voltage	$V_r$	5V	
Operating Temperature Range	$T_{opr}$	-40°C to + 85°C	
Storage Temperature Range	$T_{sto}$	-40°C to + 100°C	
Lead Soldering Temperature	$T_{sol}$	260°C / 5 Secondes	

Notes: a. Duty Ratio = 1/10, Pulse Width = 0.1ms.

b. Design of heat dissipation should be considered.